

The laboratory of back side cut protection of the silicone

BACK GRINDING TAPE 214D

Features

Back grinding tape lets you use the laboratory of back side cut (you go back and grind it) of the wafer to sometimes protect a circuit surface from pollution such as a wound, tipping (breaking) or the contamination by the external alien substance.

- In the circuit surfaces, it is the superior coherency for the irregularities wafer
- Superior easy fissility

Use Washing process to grind of the semiconductor wafer

Structure



Characteristic

Specifications Base material Polyester resin

Properties

name	Thickness (mm)	The adhesive strength	
		The strong adhesion side (N/25mm)	The weak adhesion side (N/25mm)
214D	0.135	25	15

*PET#25Lining Adherend:Stainless steel

After the pasting up, I leave you unattended 24 hours later

Pulling angle 300mm/min 180 degrees peel

User is responsible for determining whether the KGK product is fit for a particular purpose and suitable for user's method of application. Please remember that many factors can affect the use and performance of a KGK product in a particular application. The materials to be bonded with the product, the surface preparation of those materials, the product selected for use, the conditions in which the product is used, and the time and environmental conditions in which the product is expected to perform are among the many factors that can affect the use and performance of a KGK product. Given the variety of factors that can affect the use and performance of a KGK product, some of which are uniquely within the user's knowledge and control, it is essential that the user evaluate the KGK product to determine whether it is fit for a particular purpose and suitable for the user's method of application.

KGK make no warranties on above data.

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